

DATA SHEET

74LVC244A; 74LVCH244A Octal buffer/line driver with 5 V tolerant inputs/outputs; 3-state

Product specification
Supersedes data of 1998 May 20

2003 May 20

Octal buffer/line driver with 5 V tolerant inputs/outputs; 3-state

74LVC244A; 74LVCH244A

FEATURES

- 5 V tolerant inputs/outputs for interfacing with 5 V logic
- Wide supply voltage range from 1.2 to 3.6 V
- CMOS low power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5.5 V
- High-impedance when $V_{CC} = 0$ V
- Bushold on all data inputs (74LVCH244A only)
- Complies with JEDEC standard no. 8-1A
- ESD protection:
HBM EIA/JESD22-A114-A exceeds 2000 V
MM EIA/JESD22-A115-A exceeds 200 V.
- Specified from -40 to $+85$ °C and -40 to $+125$ °C.

DESCRIPTION

The 74LVC244A/74LVCH244A is a high performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3 or 5 V devices. In 3-state operation, outputs can handle 5 V. These features allow the use of these devices as translators in a mixed 3.3 and 5 V environment.

The 74LVC244A/74LVCH244A is an octal non-inverting buffer/line driver with 3-state outputs. The 3-state outputs are controlled by the output enable inputs $1\overline{OE}$ and $2\overline{OE}$. A HIGH on $n\overline{OE}$ causes the outputs to assume a high-impedance OFF-state. Schmitt-trigger action at all inputs makes the circuit highly tolerant for slower input rise and fall times.

The 244 is functionally identical to the 240, but the 240 has inverting outputs.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25$ °C; $t_r = t_f \leq 2.5$ ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PHL}/t_{PLH}	propagation delay 1An to 1Yn, 2An to 2Yn	$C_L = 50$ pF; $V_{CC} = 3.3$ V	2.8	ns
C_I	input capacitance		4.0	pF
C_{PD}	power dissipation capacitance per buffer	$V_{CC} = 3.3$ V; notes 1 and 2	10	pF

Notes

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts;

N = total load switching outputs;

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

2. The condition is $V_i = \text{GND to } V_{CC}$.

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ORDERING INFORMATION

TYPE NUMBER	PACKAGE				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74LVC244AD	-40 to +125 °C	20	SO20	plastic	SOT163-1
74LVCH244AD	-40 to +125 °C	20	SO20	plastic	SOT163-1
74LVC244ADB	-40 to +125 °C	20	SSOP20	plastic	SOT339-1
74LVCH244ADB	-40 to +125 °C	20	SSOP20	plastic	SOT339-1
74LVC244APW	-40 to +125 °C	20	TSSOP20	plastic	SOT360-1
74LVCH244APW	-40 to +125 °C	20	TSSOP20	plastic	SOT360-1
74LVC244ABQ	-40 to +125 °C	20	DHVQFN20	plastic	SOT764-1
74LVCH244ABQ	-40 to +125 °C	20	DHVQFN20	plastic	SOT764-1

FUNCTION TABLE

See note 1.

INPUT		OUTPUT
\overline{nOE}	nAn	nYn
L	L	L
L	H	H
H	X	Z

Note

1. H = HIGH voltage level;
L = LOW voltage level;
X = don't care;
Z = high-impedance OFF-state.

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PINNING

PIN	SYMBOL	DESCRIPTION
1	$1\overline{OE}$	output enable input (active LOW)
2	1A0	data input
3	2Y0	bus output
4	1A1	data input
5	2Y1	bus output
6	1A2	data input
7	2Y2	bus output
8	1A3	data input
9	2Y3	bus output
10	GND	ground (0 V)

PIN	SYMBOL	DESCRIPTION
11	2A3	bus input
12	1Y3	bus output
13	2A2	bus input
14	1Y2	bus output
15	2A1	bus input
16	1Y1	bus output
17	2A0	bus input
18	1Y0	bus output
19	$2\overline{OE}$	output enable input (active LOW)
20	V _{CC}	supply voltage

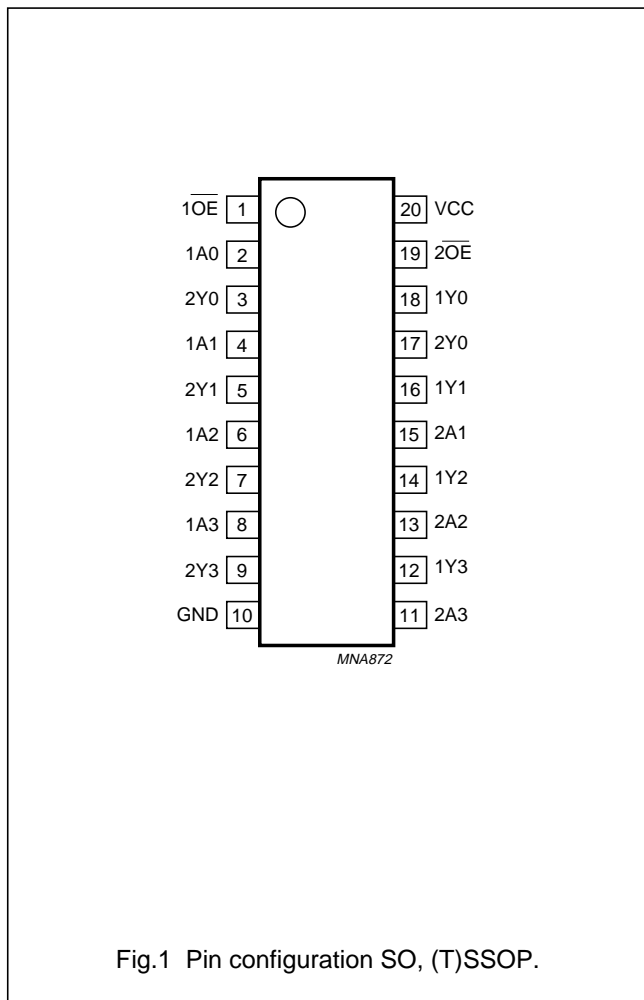
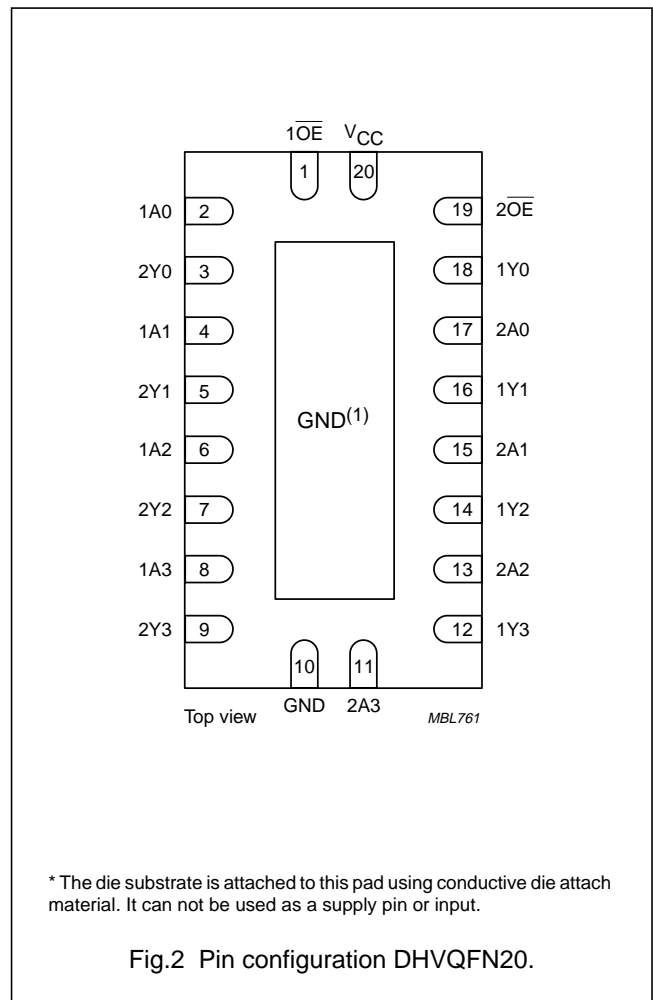


Fig.1 Pin configuration SO, (T)SSOP.



* The die substrate is attached to this pad using conductive die attach material. It can not be used as a supply pin or input.

Fig.2 Pin configuration DHVQFN20.

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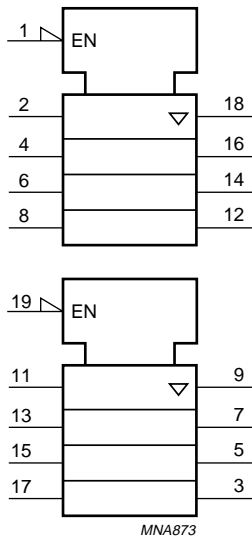


Fig.3 Logic symbol (IEEE/IEC).

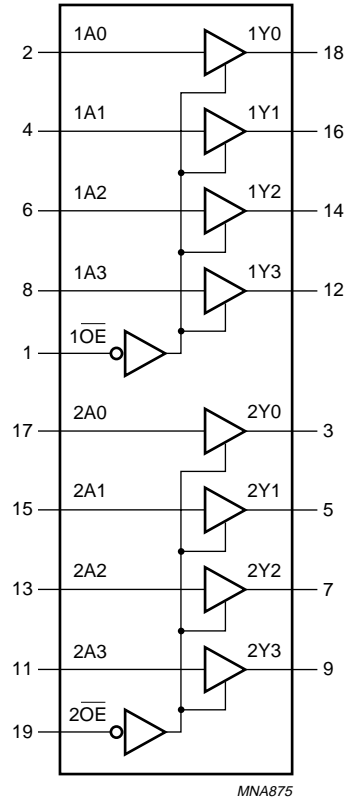


Fig.4 Functional diagram.

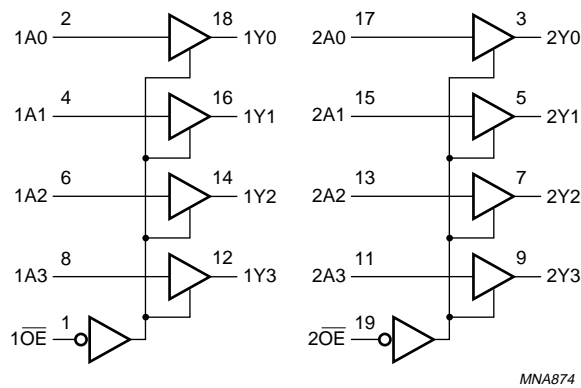


Fig.5 Logic symbol.

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RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage	for maximum speed performance	2.7	3.6	V
		for low-voltage applications	1.2	3.6	V
V _I	input voltage		0	5.5	V
V _O	output voltage	output HIGH or LOW state	0	V _{CC}	V
		output 3-state	0	5.5	V
T _{amb}	operating ambient temperature	in free air	-40	+125	°C
t _r , t _f	input rise and fall times	V _{CC} = 1.2 to 2.7 V	0	20	ns/V
		V _{CC} = 2.7 to 3.6 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CC}	supply voltage		-0.5	+6.5	V
I _{IK}	input diode current	V _I < 0	-	-50	mA
V _I	input voltage	note 1	-0.5	+6.5	V
I _{OK}	output diode current	V _O > V _{CC} or V _O < 0	-	±50	mA
V _O	output voltage	output HIGH or LOW state; note 1	-0.5	V _{CC} + 0.5	V
		output 3-state; note 1	-0.5	+6.5	V
I _O	output source or sink current	V _O = 0 to V _{CC}	-	±50	mA
I _{CC} , I _{GND}	V _{CC} or GND current		-	±100	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	power dissipation	T _{amb} = -40 to +125 °C; note 2	-	500	mW

Notes

- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- For SO20 packages: above 70 °C derate linearly with 8 mW/K.
For SSOP20 and TSSOP20 packages: above 60 °C derate linearly with 5.5 mW/K.
For DHVQFN20 packages: above 60 °C derate linearly with 5.5 mW/K.

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DC CHARACTERISTICS

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. ⁽¹⁾	MAX.	UNIT
		OTHER	V _{CC} (V)				
T_{amb} = -40 to +85 °C							
V _{IH}	HIGH-level input voltage		1.2	V _{CC}	–	–	V
			2.7 to 3.6	2.0	–	–	V
V _{IL}	LOW-level input voltage		1.2	–	–	GND	V
			2.7 to 3.6	–	–	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}	2.7 to 3.6	V _{CC} – 0.2	V _{CC}	–	V
		I _O = –100 µA	2.7	V _{CC} – 0.5	–	–	V
		I _O = –12 mA	3.0	V _{CC} – 0.6	–	–	V
		I _O = –24 mA	3.0	V _{CC} – 0.8	–	–	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}	2.7 to 3.6	–	GND	0.20	V
		I _O = 100 µA	2.7	–	–	0.40	V
		I _O = 24 mA	3.0	–	–	0.55	V
I _{LI}	input leakage current	V _I = 5.5 V or GND; notes 2	3.6	–	±0.1	±5	µA
I _{OZ}	3-state output OFF-state current	V _I = V _{IH} or V _{IL} ; V _O = 5.5 V or GND; notes 2	3.6	–	0.1	±5	µA
I _{off}	power-off leakage supply current	V _I or V _O = 5.5 V	0.0	–	0.1	±10	µA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0	3.6	–	0.1	10	µA
ΔI _{CC}	additional quiescent supply current per input pin	V _I = V _{CC} – 0.6 V; I _O = 0	2.7 to 3.6	–	5	500	µA
I _{BH(L)}	bushold LOW sustaining current	V _I = 0.8 V; notes 3 and 4	3.0	75	–	–	µA
I _{BH(H)}	bushold HIGH sustaining current	V _I = 2.0 V; notes 3 and 4	3.0	–75	–	–	µA
I _{BH(LO)}	bushold LOW overdrive current	notes 3 and 5	3.6	500	–	–	µA
I _{BH(HO)}	bushold HIGH overdrive current	notes 3 and 5	3.6	–500	–	–	µA

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SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. ⁽¹⁾	MAX.	UNIT
		OTHER	V _{CC} (V)				
T_{amb} = -40 to +125 °C							
V _{IH}	HIGH-level input voltage		1.2	V _{CC}	–	–	V
			2.7 to 3.6	2.0	–	–	V
V _{IL}	LOW-level input voltage		1.2	–	–	GND	V
			2.7 to 3.6	–	–	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}	2.7 to 3.6	V _{CC} – 0.3	–	–	V
		I _O = –100 μA	2.7	V _{CC} – 0.65	–	–	V
		I _O = –12 mA	3.0	V _{CC} – 0.75	–	–	V
		I _O = –18 mA	3.0	V _{CC} – 1	–	–	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}	2.7 to 3.6	–	–	0.3	V
		I _O = 100 μA	2.7	–	–	0.6	V
		I _O = 12 mA	3.0	–	–	0.8	V
		I _O = 24 mA					
I _{LI}	input leakage current	V _I = 5.5 V or GND; notes 2	3.6	–	–	±20	μA
I _{OZ}	3-state output OFF-state current	V _I = V _{IH} or V _{IL} ; V _O = 5.5 V or GND; notes 2	3.6	–	–	±20	μA
I _{off}	power-off leakage supply current	V _I or V _O = 5.5 V	0.0	–	–	±20	μA
I _{CC}	quiescent supply current	V _I = V _{CC} or GND; I _O = 0	3.6	–	–	40	μA
ΔI _{CC}	additional quiescent supply current per input pin	V _I = V _{CC} – 0.6 V; I _O = 0	2.7 to 3.6	–	–	5000	μA
I _{BH(L)}	bushold LOW sustaining current	V _I = 0.8 V; notes 3 and 4	3.0	60	–	–	μA
I _{BH(H)}	bushold HIGH sustaining current	V _I = 2.0 V; notes 3 and 4	3.0	–60	–	–	μA
I _{BH(LO)}	bushold LOW overdrive current	notes 3 and 5	3.6	500	–	–	μA
I _{BH(HO)}	bushold HIGH overdrive current	notes 3 and 5	3.6	–500	–	–	μA

Notes

1. All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.
2. For bushold parts, the bushold circuit is switched off when V_I > V_{CC} allowing 5.5 V on the input pin.
3. Valid for data inputs of bushold parts (74LVCH244A) only. For data inputs only, control inputs do not have a bushold circuit.
4. The specified sustaining current at the data inputs do not have a bushold circuit.
5. The specified overdrive current at the data input forces the data input to the opposite logic input state.

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AC CHARACTERISTICS

GND = 0 V; $t_r = t_f \leq 2.5$ ns.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	V _{CC} (V)				
T_{amb} = -40 to +85 °C							
t _{PHL} /t _{PLH}	propagation delay 1An to 1Yn, 2An to 2Yn	see Figs 6 and 8	1.2	–	17.0	–	ns
			2.7	1.5	3.3	6.9	ns
			3.0 to 3.6	1.5	2.8 ⁽¹⁾	5.9	ns
t _{PZH} /t _{PZL}	3-state output enable time 1 \overline{OE} to 1Yn, 2 \overline{OE} to 2Yn	see Figs 7 and 8	1.2	–	24.0	–	ns
			2.7	1.5	3.3	8.6	ns
			3.0 to 3.6	1.0	3.4 ⁽¹⁾	7.6	ns
t _{PHZ} /t _{PLZ}	3-state output disable time 1 \overline{OE} to 1Yn, 2 \overline{OE} to 2Yn	see Figs 7 and 8	1.2	–	9.0	–	ns
			2.7	1.5	3.2	6.8	ns
			3.0 to 3.6	1.5	2.9 ⁽¹⁾	5.8	ns
t _{sk(0)}	skew	note 2		–	–	1.0	1.5
T_{amb} = -40 to +125 °C							
t _{PHL} /t _{PLH}	propagation delay 1An to 1Yn, 2An to 2Yn	see Figs 6 and 8	1.2	–	–	–	ns
			2.7	1.5	–	9.0	ns
			3.0 to 3.6	1.5	–	7.5	ns
t _{PZH} /t _{PZL}	3-state output enable time 1 \overline{OE} to 1Yn, 2 \overline{OE} to 2Yn	see Figs 7 and 8	1.2	–	–	–	ns
			2.7	1.5	–	11	ns
			3.0 to 3.6	1.0	–	9.5	ns
t _{PHZ} /t _{PLZ}	3-state output disable time 1 \overline{OE} to 1Yn, 2 \overline{OE} to 2Yn	see Figs 7 and 8	1.2	–	–	–	ns
			2.7	1.5	–	8.5	ns
			3.0 to 3.6	1.5	–	7.5	ns
t _{sk(0)}	skew	note 2		–	–	1.5	ns

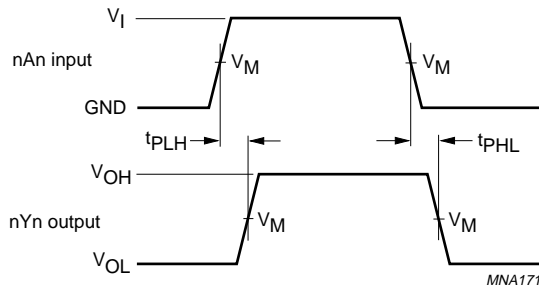
Notes

1. All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.
2. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

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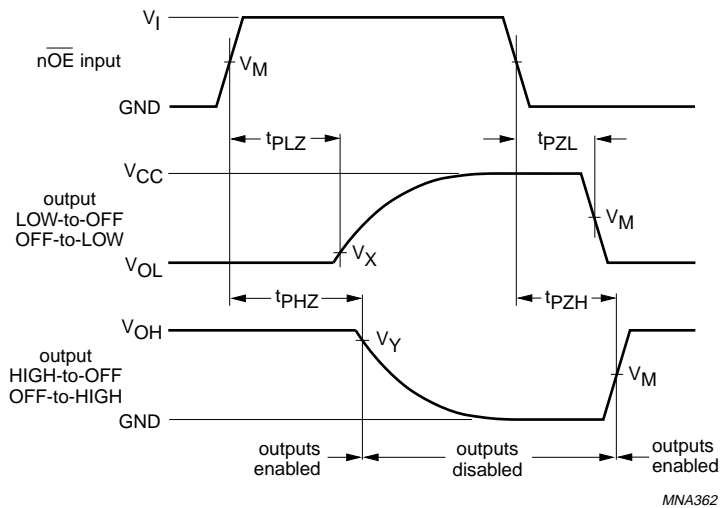
AC WAVEFORMS



$V_M = 1.5\text{ V}$ at $V_{CC} \geq 2.7\text{ V}$.
 $V_M = 0.5V_{CC}$ at $V_{CC} < 2.7\text{ V}$.

V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig.6 Input nAn to output nYn propagation delays.



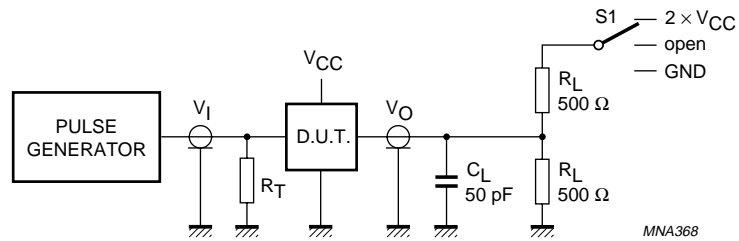
$V_M = 1.5\text{ V}$ at $V_{CC} \geq 2.7\text{ V}$.
 $V_M = 0.5V_{CC}$ at $V_{CC} < 2.7\text{ V}$.
 $V_X = V_{OL} + 0.3\text{ V}$ at $V_{CC} \geq 2.7\text{ V}$;
 $V_X = V_{OL} + 0.1V_{CC}$ at $V_{CC} < 2.7\text{ V}$.
 $V_Y = V_{OH} + 0.3\text{ V}$ at $V_{CC} \geq 2.7\text{ V}$;
 $V_Y = V_{OH} + 0.1V_{CC}$ at $V_{CC} < 2.7\text{ V}$.

V_{OL} and V_{OH} are typical output voltage drop that occur with the output load.

Fig.7 3-state enable and disable times.

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SWITCH POSITION	
TEST	S1
t_{PLH}/t_{PHL}	open
t_{PLZ}/t_{PZL}	$2 \times V_{CC}$
t_{PHZ}/t_{PZH}	GND

V_{CC}	V_{IN}
<2.7 V	V_{CC}
2.7 to 3.6 V	2.7 V

Definitions for test circuits:

R_L = Load resistor.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to Z_o of the pulse generator.

Fig.8 Load circuitry for switching times.

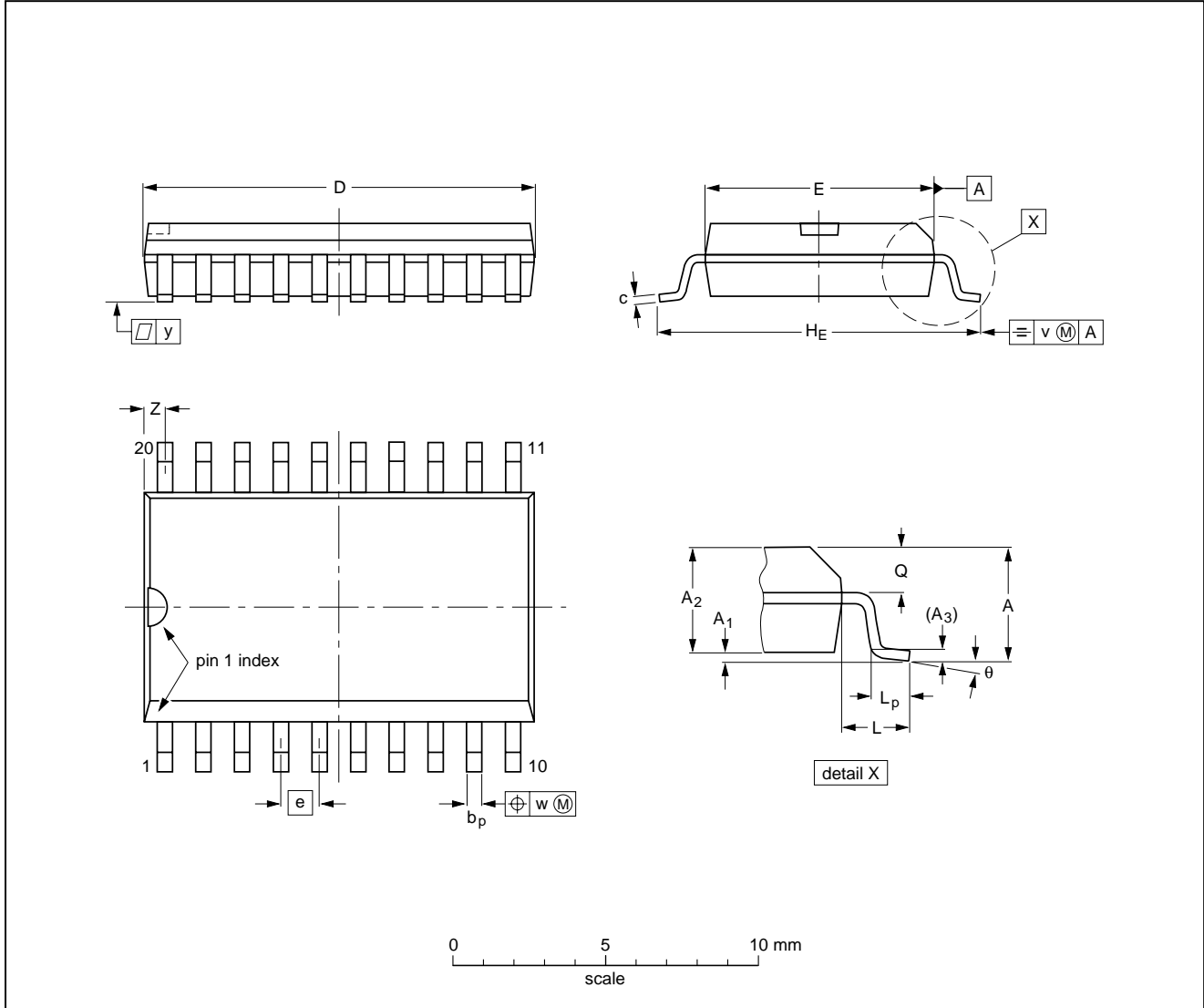
Octal buffer/line driver with 5 V tolerant inputs/outputs; 3-state

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PACKAGE OUTLINES

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

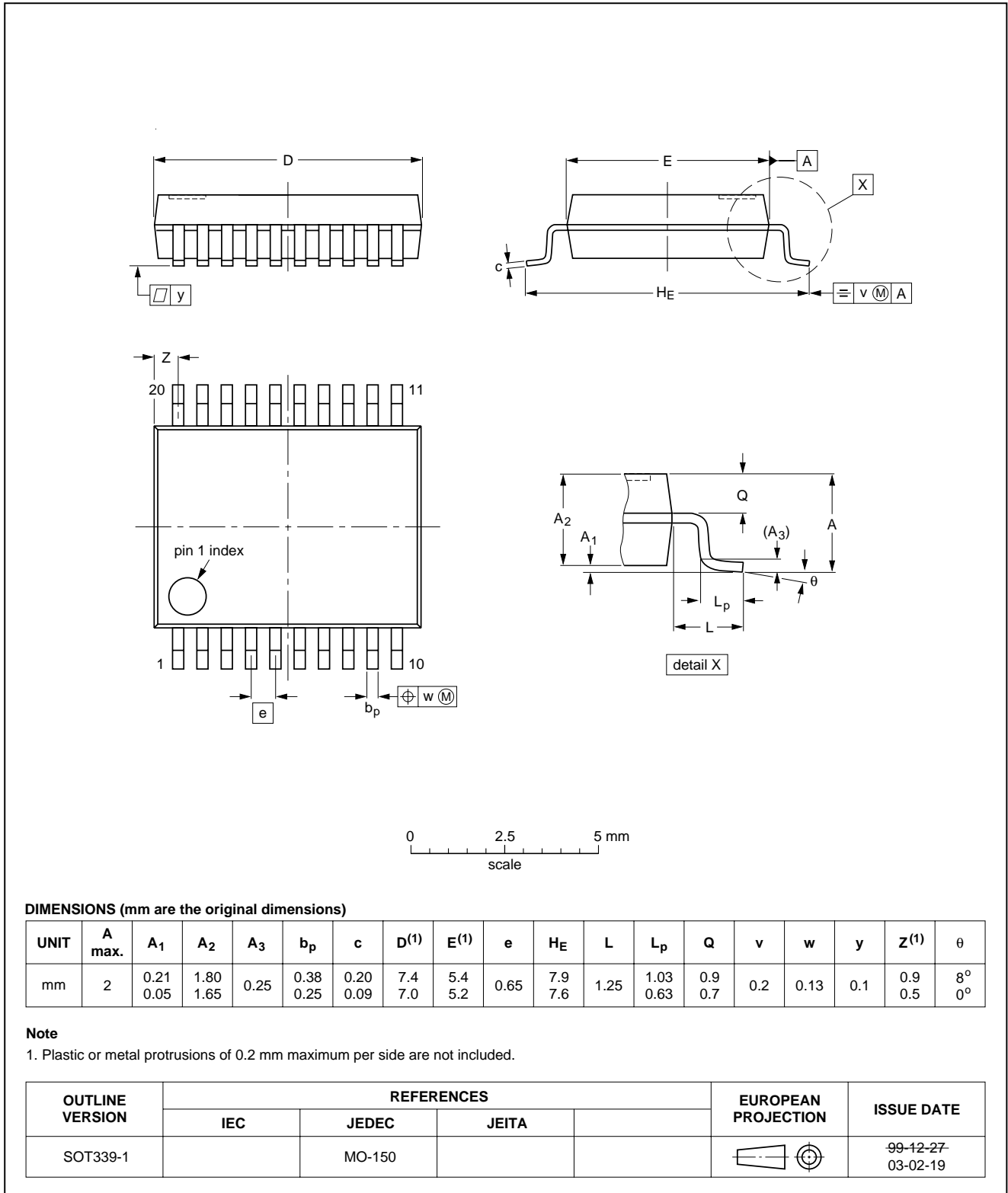
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	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				99-12-27 03-02-19

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SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

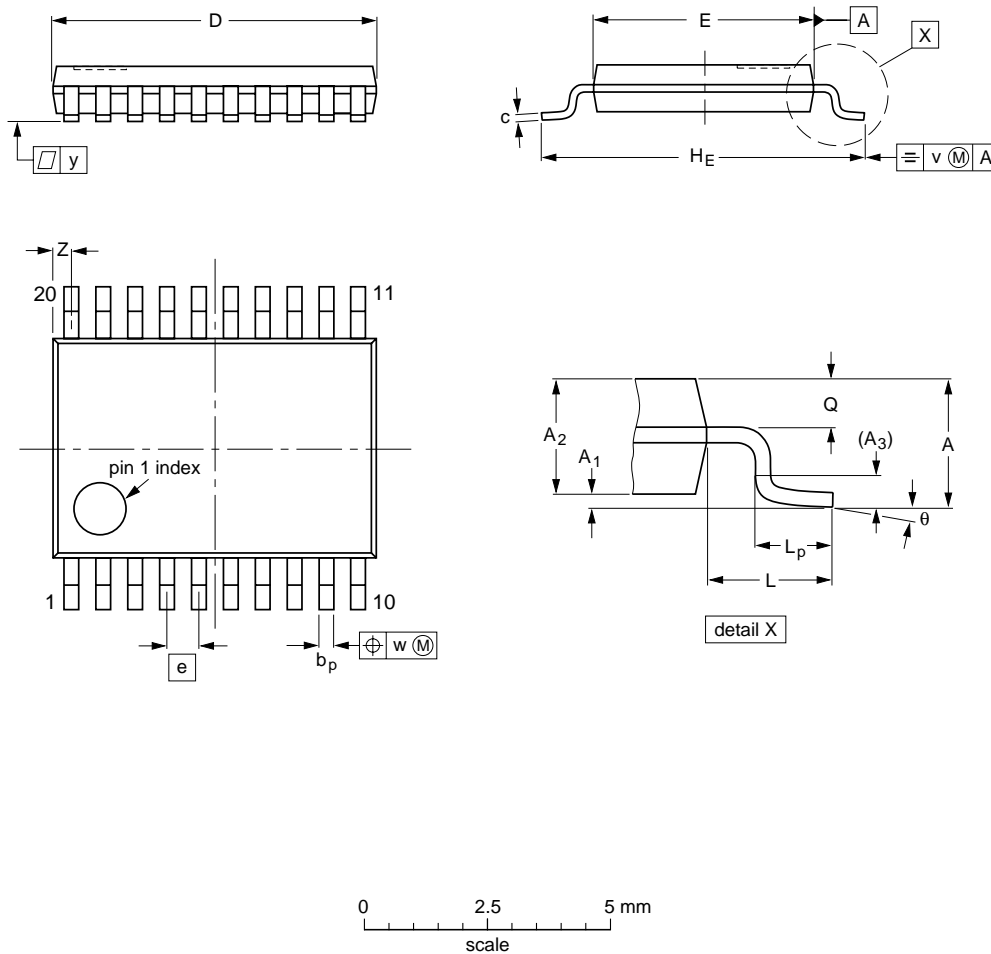


Octal buffer/line driver with 5 V tolerant inputs/outputs; 3-state

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TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

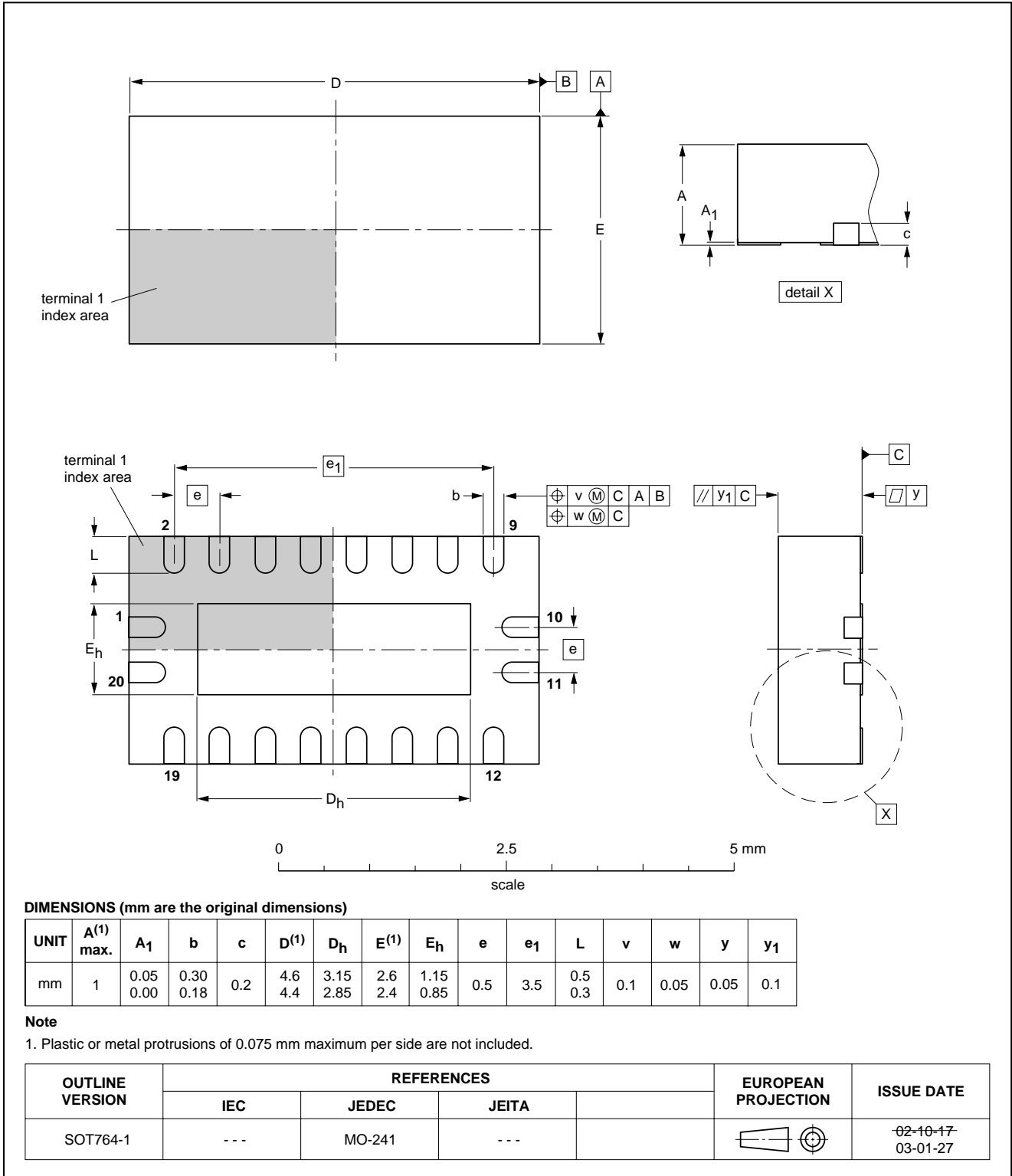
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	IEC	JEDEC	JEITA			
SOT360-1		MO-153				99-12-27 03-02-19

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DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1



Octal buffer/line driver with 5 V tolerant inputs/outputs; 3-state

74LVC244A; 74LVCH244A

SOLDERING

Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 to 250 °C. The top-surface temperature of the packages should preferably be kept below 220 °C for thick/large packages, and below 235 °C for small/thin packages.

Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is **preferred** to be parallel to the transport direction of the printed-circuit board;
 - smaller than 1.27 mm, the footprint longitudinal axis **must** be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

- For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

Octal buffer/line driver with 5 V tolerant inputs/outputs; 3-state

74LVC244A; 74LVCH244A

Suitability of surface mount IC packages for wave and reflow soldering methods

PACKAGE ⁽¹⁾	SOLDERING METHOD	
	WAVE	REFLOW ⁽²⁾
BGA, LBGA, LFBGA, SQFP, TFBGA, VFBGA	not suitable	suitable
DHVQFN, HBCC, HBGA, HLQFP, HSQFP, HSOP, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable ⁽³⁾	suitable
PLCC ⁽⁴⁾ , SO, SOJ	suitable	suitable
LQFP, QFP, TQFP	not recommended ⁽⁴⁾⁽⁵⁾	suitable
SSOP, TSSOP, VSO	not recommended ⁽⁶⁾	suitable

Notes

1. For more detailed information on the BGA packages refer to the “(LF)BGA Application Note” (AN01026); order a copy from your Philips Semiconductors sales office.
2. All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the “Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods”.
3. These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
4. If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
5. Wave soldering is suitable for LQFP, TQFP and QFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
6. Wave soldering is suitable for SSOP and TSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.

Octal buffer/line driver with 5 V tolerant inputs/outputs; 3-state

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DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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Notes

1. Please consult the most recently issued data sheet before initiating or completing a design.
2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.
3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Octal buffer/line driver with 5 V tolerant
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Contact information

For additional information please visit <http://www.semiconductors.philips.com>. Fax: +31 40 27 24825

For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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